Standard Features

- 5.0V low-leakage CMOS transistors
- 17V and 40V high-voltage LDMOS transistors
- · High-density, double-poly memory cell
- Isolated NMOS and LDMOS transistors
- Analog Resistors
- Dual Poly Capacitor
- Mono-silicon capacitors
- 3 layer metal
- · Isolated and folded bond pads

Applications

- Power management integrated circuits
- We'High performance mixed-signal with embedded memory
 - Motor/motion control
 - Automotive monitor and control circuitry

Description

Atmel's AT35700, 0.35um, high-voltage CMOS foundry technology process was developed for mixed-signal and power management applications. The technology has LDMOS transistors capable of 17V and 40V operation and has 5.0V low-leakage CMOS transistors. The low-leakage CMOS has been engineered to minimize subthreshold leakage currents making this technology ideal for portable electronic devices. Isolated NMOS and LDMOS transistors are included to minimize circuit noise. A large selection of on-chip analog resistors and capacitors are included to reduce off-chip component requirements. The technology supports placement of ESD and I/O transistors under the bond pads, thus minimizing the die size.

Included is Atmel's reliable double-poly, high-density memory cell. The cell can be used to create parallel EEPROM, serial EEPROM or Pseudo FLASH memory designs. Having embedded EEPROM provides large data storage capability as required in monitor and control applications and eliminates the need for additional memory chips.



0.35um, 40.0V HV CMOS Foundry Technology

AT35700

Preliminary

5166A-HVCMOS-5/06





Atmel's AT35700 0.35um HV CMOS Foundry Process Specifications

Table 1. CMOS Specifications

CMOS	Drawn Size (um)	V _t (V)	BVdss (V)	Max Op (V)	Tox (angstrom)
LV NMOS	0.49	0.85	>6	6	110
LV PMOS	0.49	-0.9	<-6	-6	110
HV NMOS in Substrate/No Vt II	1.68	0.05	>15	10	275
HV NMOS in Substrate/Vt II	1.33	0.6	>12	10	275
HV NMOS in HV P-Well/No Vt II	1.54	0.3	>14	10	275
HV PMOS in HV N-Well/Vt II	1.12	-0.85	<-12	-12	275
HV PMOS in LV P-Well	1.505	-0.85	<-16	-12	275
HV BN+ NMOS in Substrate/No Vt II	2.765	-0.15	>16	16	275
HV BN+ NMOS in Substrate/Vt II	2.66	0.55	>16	12	275
HV BN+ NMOS in HV P-Well/No Vt II	2.765	0.3	>16	16	275
Isolated NMOS (NMOS in SVNWELL)	0.49	0.85	>6	6	110
LDNMOS	Note 1	Note 1	>40	40	275
LDPMOS	Note 1	Note 1	<-40	40	275

Note: 1. See DRM

Table 2.Resistor Specifications

Resistor	N-Well	N-LDD	Poly 2	BN+ in Poly 1	N+ in Poly 2	P+ in Poly 2
ρ(Ω/■)	3200	1500	135	300	100	170

 Table 3.
 Capacitor Specifications

Capacitor	Capacitance (fF/um²)	Equivalent Thickness (A)	Max Op (V)
Poly2 to Poly1 (ONO)	1.55	215	16
Poly2 to BN+ (SiO2)	1.15	290	16
Poly2 to BN+ (SiO2)	2.5	130	6
Poly2 to Poly1			40
Poly2 to LV N-Well	3	110	6



Atmel Corporation

2325 Orchard Parkway San Jose, CA 95131, USA Tel: 1(408) 441-0311

Fax: 1(408) 487-2600

Regional Headquarters

Europe

Atmel Sarl

Route des Arsenaux 41

www.Case Rostale 80 CH-1705 Fribourg

Switzerland

Tel: (41) 26-426-5555 Fax: (41) 26-426-5500

Asia

Room 1219 Chinachem Golden Plaza 77 Mody Road Tsimshatsui

East Kowloon Hong Kong

Tel: (852) 2721-9778 Fax: (852) 2722-1369

Japan

9F, Tonetsu Shinkawa Bldg. 1-24-8 Shinkawa Chuo-ku, Tokyo 104-0033

Japan

Tel: (81) 3-3523-3551 Fax: (81) 3-3523-7581

Atmel Operations

Memory

2325 Orchard Parkway San Jose, CA 95131, USA Tel: 1(408) 441-0311 Fax: 1(408) 436-4314

Microcontrollers

2325 Orchard Parkway San Jose, CA 95131, USA Tel: 1(408) 441-0311 Fax: 1(408) 436-4314

La Chantrerie BP 70602

44306 Nantes Cedex 3, France

Tel: (33) 2-40-18-18-18 Fax: (33) 2-40-18-19-60

ASIC/ASSP/Smart Cards

Zone Industrielle 13106 Rousset Cedex, France

Tel: (33) 4-42-53-60-00 Fax: (33) 4-42-53-60-01

1150 East Cheyenne Mtn. Blvd. Colorado Springs, CO 80906, USA

Tel: 1(719) 576-3300 Fax: 1(719) 540-1759

Scottish Enterprise Technology Park Maxwell Building

East Kilbride G75 0QR, Scotland

Tel: (44) 1355-803-000

Fax: (44) 1355-242-743

Literature Requests

www.atmel.com/literature

RF/Automotive

Theresienstrasse 2 Postfach 3535 74025 Heilbronn, Germany

Tel: (49) 71-31-67-0 Fax: (49) 71-31-67-2340

1150 East Cheyenne Mtn. Blvd. Colorado Springs, CO 80906, USA

Tel: 1(719) 576-3300 Fax: 1(719) 540-1759

Biometrics/Imaging/Hi-Rel MPU/ High-Speed Converters/RF Datacom

Avenue de Rochepleine

BP 123

38521 Saint-Egreve Cedex, France

Tel: (33) 4-76-58-30-00 Fax: (33) 4-76-58-34-80

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